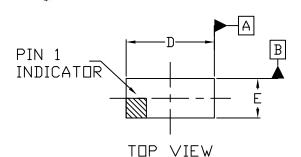
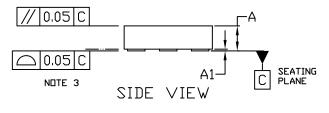


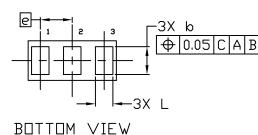
DSN3 0.76x0.34 (0301) CASE 152BA

ISSUE A

DATE 18 MAR 2021



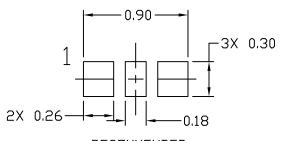




NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009, CONTROLLING DIMENSION: MILLIMETERS COPLANARITY APPLIES TO ALL PADS

	MILLIMETERS		
DIM	MIN.	N□M.	MAX.
Α	0.17	0.20	0.23
A1	0.00		0.03
b	0.22	0.24	0.26
D	0.73	0.76	0.79
E	0.31	0.34	0.37
е	0.275 BSC		
L	0.13	0.15	0.17



RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

GENERIC MARKING DIAGRAM*



X = Specific Device Code

M = Month Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON23592H	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	DSN3 0.76x0.34 (0301)		PAGE 1 OF 1	

onsemi and Onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries, onsemi reserves brisefin and of 160 m are trademarked so defined values of services and of the confined values and of the values of the confined values and of the values of the confined values and of the values of the v special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.